

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. (previously presented) A liquid crystal device comprising:  
a pair of substrates opposed to one another via a seal member;  
electrodes formed within an inside area of the seal member on one substrate of the pair of substrates; and  
a first insulation film disposed on the electrodes,  
wherein in an area outside of the seal member the one substrate includes a protruding area beyond an end portion of the other substrate, and the protruding area includes wiring lines connected to the electrodes, and  
wherein at least a part of the wiring lines and a part of an area that is free of the wiring lines in the protruding area of the one substrate are coated with a second insulation film made of the same material as the first insulation film.
2. (previously presented) The liquid crystal device according to Claim 1,  
wherein the wiring lines comprise a conductive connection member electrically connected to an integrated circuit or to a wiring member, the conductive connection member is free of the second insulation film.
3. (previously presented) The liquid crystal device according to Claim 2,  
wherein the conductive connection member is connected to the integrated circuit or to the wiring member via an anisotropic conductive film, and  
wherein an edge of the anisotropic conductive film is formed on the second insulation film.

4. (previously presented) A method for manufacturing a liquid crystal device having a pair of substrates opposed to one another via a seal member, one substrate of the pair of substrates including a protruding area beyond an end portion of the other substrate, the method comprising the steps of:

forming electrodes on the one substrate of the pair of substrates and wiring lines connected to the electrodes on the protruding area; and

forming an insulation film covering at least a part of the electrodes and the wiring lines and a part of an area that is free of the wiring lines in the protruding area of the one substrate.

5. (previously presented) The method for manufacturing a liquid crystal device according to Claim 4,

wherein the wiring lines comprise a conductive connection member electrically connected to an integrated circuit or to a wiring member, the conductive connection member being free from the insulation film.

6. (original) The method for manufacturing a liquid crystal device according to Claim 5,

wherein the conductive connection member is connected to the integrated circuit or to the wiring member via an anisotropic conductive film, and

wherein an edge of the anisotropic conductive film overlaps the insulation film.

7. (previously presented) The method for manufacturing a liquid crystal device according to Claim 6,

wherein an edge of the insulation film is formed along one edge of a first positioning mark, and

wherein the edge of the anisotropic conductive film is formed along one edge of a second positioning mark.

8. (previously presented) A liquid crystal device comprising:  
a pair of substrates opposed to one another via a seal member;  
electrodes formed within an inside area of the seal member on one substrate of the pair of substrates;

an overcoat layer formed on the electrodes; and

an orientation film formed on the overcoat layer,

wherein in an area outside of the seal member the one substrate includes a protruding area beyond an end portion of the other substrate that has two corners formed on the one substrate in plan view, the protruding area including wiring lines connected to the electrodes and the wiring lines covered with the overcoat layer and the orientation film formed thereon, and

wherein at least a part of the wiring lines and at least one of the corners of the protruding area are coated with a protective film including the overcoat layer and the orientation film,

and

wherein the entire overcoat layer is covered with the orientation film on the protruding area.

9. (previously presented) A method for manufacturing a liquid crystal device having a pair of substrates opposed to one another via a seal member, one substrate of

the pair of substrates including a protruding area beyond an end portion of the other substrate, the method comprising the steps of:

forming electrodes on one substrate of the pair of substrates and wiring lines connected to the electrodes on the protruding area which has two corners formed on the one substrate in plan view;

forming an overcoat layer on the electrodes, the wiring lines, and at least one of the corners of the protruding area;

forming an orientation film on the overcoat layer; and

applying a rubbing treatment to the orientation film,

wherein the entire overcoat layer is covered with the orientation film on the protruding area.

10. (previously presented) A liquid crystal device comprising:  
a pair of substrates opposed to one another via a seal member;  
electrodes formed within an inside area of the seal member on the pair of substrates; and

an insulation layer formed on the electrodes of one substrate of the pair of substrates,

wherein in an area outside of the seal member the one substrate includes a protruding area beyond an end portion of the other substrate;

wherein the protruding area includes wiring lines electrically connected to the electrodes provided on the other substrate via a conductive connection member in the seal member, at least a part of the wiring lines being coated with the insulation layer, and

wherein the wiring lines immediately beneath the conductive connection member are free of the insulation layer.

11. (previously presented) The liquid crystal device according to Claim 10, wherein the insulation layer comprises at least either an overcoat layer covering the electrodes, or an orientation film formed above the electrodes.

12. (previously presented) A liquid crystal device comprising:  
a pair of substrates opposed to one another via a seal member;  
electrodes formed within an inner area of the seal member on one substrate of the pair of substrates; and  
an insulation film formed on the electrodes,  
wherein in an area outside of the seal member the one substrate includes a protruding area beyond an end portion of the other substrate, the protruding area including a packaging area in which wiring lines connected to the electrodes and to an outer circuit including an IC for addressing the liquid crystal device are packaged, at least a part of the wiring lines are coated with an insulating film made of the same material as the insulation film formed on the electrodes, and a mold member is disposed on the wiring lines formed between the packaging area and the seal member, the entirety of the mold member being disposed between the seal member and the IC.

13. (cancelled).

14. (previously presented) A liquid crystal device comprising:  
a pair of substrates opposed to one another via a seal member; and  
an orientation film provided at an inner face side of one substrate of the pair of substrates,

wherein in an area outside of the seal member the one substrate includes a protruding area including wiring lines extending out of an inside area of the seal member,

wherein at least a part of the wiring lines is covered with an insulation film,

at least an edge of the insulation film being covered with the orientation film, and

wherein the protruding area includes a positioning mark, the positioning mark defines both positions of the edge of the insulation film and an edge of the orientation film.

15. (previously presented) The liquid crystal device according to Claim 14, wherein in an area inside of the seal member the one substrate includes electrodes for applying an electric field to the liquid crystal, the orientation film being provided on the electrodes, and

wherein a protective film is provided between the electrodes and the orientation film, the protective film being made of a same material as the insulation film.

16. (original) The liquid crystal device according to Claim 14, wherein the orientation film is formed so as to cover the entire insulation film.

17. (previously presented) The liquid crystal device according to Claim 14, wherein the positioning mark includes two outer edges, the insulation film is formed along one outer edge of the positioning mark, and the orientation film is formed along another outer edge of the positioning mark.

18. (previously presented) The liquid crystal device according to Claim 17, wherein the one outer edge is opposite the another outer edge.

19. (previously presented) The liquid crystal device according to Claim 14, wherein the positioning mark is made of the same material as the wiring lines.

20. (previously presented) A method for manufacturing a liquid crystal device having a pair of substrates opposed to one another via a seal member, one substrate of the pair of substrates including a protruding area beyond an end portion of the other substrate, the method comprising the steps of:

forming electrodes on the one substrate and wiring lines connected to the electrodes on the protruding area;

forming an insulation film covering at least a part of the electrodes and the wiring lines;

forming an orientation film on the insulation film; and

forming a positioning mark on the one substrate,

wherein the insulation film is formed along one outer edge of the positioning mark, the orientation film is formed along another outer edge of the positioning mark, and

an edge of the insulation film is covered with the orientation film on the protruding area.

21. (cancelled).

22. (previously presented) The liquid crystal device according to Claim 1, wherein the protruding area includes a packaging area in which wiring lines connected to the electrodes and to an outer circuit including an IC for addressing the liquid crystal device are packaged, and

wherein the packaging area is free of the second insulation film.

23. (previously presented) The liquid crystal device according to Claim 2,  
wherein terminals connected to the integrated circuit are formed on the  
protruding area, and  
the terminals are free of the second insulation film.

24. (previously presented) The liquid crystal device according to Claim 3,  
wherein the insulation film is formed along one edge of a first positioning mark,  
and  
wherein the anisotropic conductive film is formed along one edge of a second  
positioning mark.